

To our customers,

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## Old Company Name in Catalogs and Other Documents

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On April 1<sup>st</sup>, 2010, NEC Electronics Corporation merged with Renesas Technology Corporation, and Renesas Electronics Corporation took over all the business of both companies. Therefore, although the old company name remains in this document, it is a valid Renesas Electronics document. We appreciate your understanding.

Renesas Electronics website: <http://www.renesas.com>

April 1<sup>st</sup>, 2010  
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

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# MOS FIELD EFFECT TRANSISTOR NP82N055MUG, NP82N055NUG

## SWITCHING N-CHANNEL POWER MOS FET

### DESCRIPTION

The NP82N055MUG and NP82N055NUG are N-channel MOS Field Effect Transistors designed for high current switching applications.

### ORDERING INFORMATION

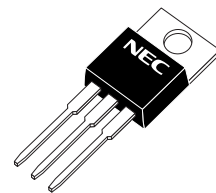
| PART NUMBER                        | LEAD PLATING  | PACKING   | PACKAGE                     |
|------------------------------------|---------------|-----------|-----------------------------|
| NP82N055MUG-S18-AY <sup>Note</sup> | Pure Sn (Tin) | Tube      | TO-220 (MP-25K) typ. 1.9 g  |
| NP82N055NUG-S18-AY <sup>Note</sup> |               | 50 p/tube | TO-262 (MP-25SK) typ. 1.8 g |

**Note** Pb-free (This product does not contain Pb in the external electrode.)

### FEATURES

- Non logic level
- Super low on-state resistance  
 $R_{DS(on)} = 6.0 \text{ m}\Omega \text{ MAX. (} V_{GS} = 10 \text{ V, } I_D = 41 \text{ A)}$
- High current rating  
 $I_{D(DC)} = \pm 82 \text{ A}$
- Low input capacitance  
 $C_{iss} = 6400 \text{ pF TYP.}$
- Designed for automotive application and AEC-Q101 qualified

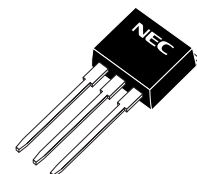
(TO-220)



### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

|   |                       |             |    |
|---|-----------------------|-------------|----|
| Drain to Source Voltage (V <sub>GS</sub> = 0 V) | V <sub>DSS</sub>      | 55          | V  |
| Gate to Source Voltage (V <sub>DS</sub> = 0 V)  | V <sub>GSS</sub>      | ±20         | V  |
| Drain Current (DC) (T <sub>C</sub> = 25°C)      | I <sub>D(DC)</sub>    | ±82         | A  |
| Drain Current (pulse) <sup>Note1</sup>          | I <sub>D(pulse)</sub> | ±328        | A  |
| Total Power Dissipation (T <sub>C</sub> = 25°C) | P <sub>T1</sub>       | 143         | W  |
| Total Power Dissipation (T <sub>A</sub> = 25°C) | P <sub>T2</sub>       | 1.8         | W  |
| Channel Temperature                             | T <sub>ch</sub>       | 175         | °C |
| Storage Temperature                             | T <sub>stg</sub>      | -55 to +175 | °C |
| Repetitive Avalanche Current <sup>Note2</sup>   | I <sub>AR</sub>       | 38          | A  |
| Repetitive Avalanche Energy <sup>Note2</sup>    | E <sub>AR</sub>       | 144         | mJ |

(TO-262)



**Notes 1.** PW ≤ 10 μs, Duty Cycle ≤ 1%

**2.** T<sub>ch</sub> ≤ 150°C, R<sub>G</sub> = 25 Ω

### THERMAL RESISTANCE

|                                       |                       |      |      |
|---------------------------------------|-----------------------|------|------|
| Channel to Case Thermal Resistance    | R <sub>th(ch-C)</sub> | 1.05 | °C/W |
| Channel to Ambient Thermal Resistance | R <sub>th(ch-A)</sub> | 83.3 | °C/W |

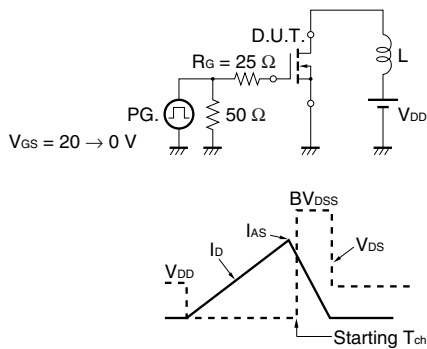
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**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)**

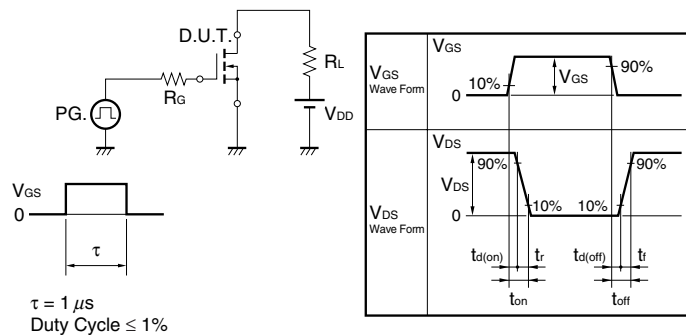
| CHARACTERISTICS                                     | SYMBOL              | TEST CONDITIONS   | MIN. | TYP. | MAX. | UNIT |
|---|---------------------|---|------|------|------|------|
| Zero Gate Voltage Drain Current                     | I <sub>DSS</sub>    | V <sub>DS</sub> = 55 V, V <sub>GS</sub> = 0 V   |      |      | 1    | μA   |
| Gate Leakage Current                                | I <sub>GSS</sub>    | V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V  |      |      | ±100 | nA   |
| Gate to Source Threshold Voltage                    | V <sub>GS(th)</sub> | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA                                       | 2.0  |      | 4.0  | V    |
| Forward Transfer Admittance <sup>Note</sup>         | y <sub>fs</sub>     | V <sub>DS</sub> = 5 V, I <sub>D</sub> = 41 A  | 19   | 54   |      | S    |
| Drain to Source On-state Resistance <sup>Note</sup> | R <sub>DS(on)</sub> | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 41 A   |      | 4.8  | 6.0  | mΩ   |
| Input Capacitance                                   | C <sub>iss</sub>    | V <sub>DS</sub> = 25 V,<br>V <sub>GS</sub> = 0 V,<br>f = 1 MHz                                    |      | 6400 | 9600 | pF   |
| Output Capacitance                                  | C <sub>oss</sub>    |   |      | 465  | 700  | pF   |
| Reverse Transfer Capacitance                        | C <sub>rss</sub>    |   |      | 275  | 500  | pF   |
| Turn-on Delay Time                                  | t <sub>d(on)</sub>  | V <sub>DD</sub> = 28 V, I <sub>D</sub> = 41 A,<br>V <sub>GS</sub> = 10 V,<br>R <sub>G</sub> = 0 Ω |      | 40   | 90   | ns   |
| Rise Time   | t <sub>r</sub>      |   |      | 93   | 240  | ns   |
| Turn-off Delay Time                                 | t <sub>d(off)</sub> |   |      | 72   | 150  | ns   |
| Fall Time   | t <sub>f</sub>      |   |      | 10   | 30   | ns   |
| Total Gate Charge                                   | Q <sub>G</sub>      | V <sub>DD</sub> = 44 V,<br>V <sub>GS</sub> = 10 V,<br>I <sub>D</sub> = 82 A                       |      | 106  | 160  | nC   |
| Gate to Source Charge                               | Q <sub>GS</sub>     |   |      | 29   |      | nC   |
| Gate to Drain Charge                                | Q <sub>GD</sub>     |   |      | 35   |      | nC   |
| Body Diode Forward Voltage <sup>Note</sup>          | V <sub>F(S-D)</sub> | I <sub>F</sub> = 82 A, V <sub>GS</sub> = 0 V  |      | 0.9  | 1.5  | V    |
| Reverse Recovery Time                               | t <sub>rr</sub>     | I <sub>F</sub> = 82 A, V <sub>GS</sub> = 0 V,<br>di/dt = 100 A/μs                                 |      | 42   |      | ns   |
| Reverse Recovery Charge                             | Q <sub>rr</sub>     |   |      | 57   |      | nC   |

**Note** Pulsed test

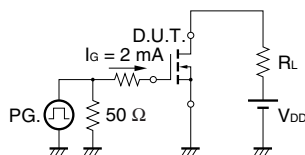
**TEST CIRCUIT 1 AVALANCHE CAPABILITY**



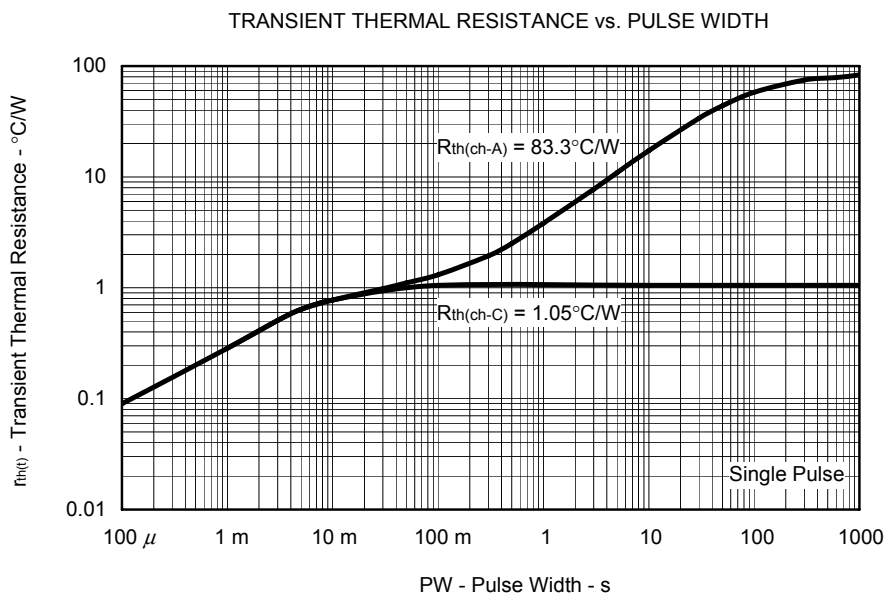
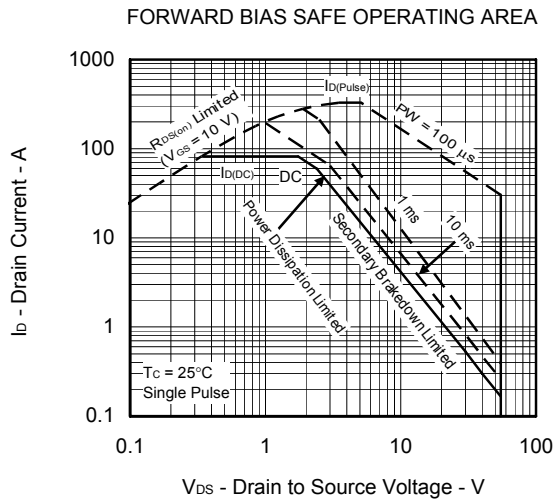
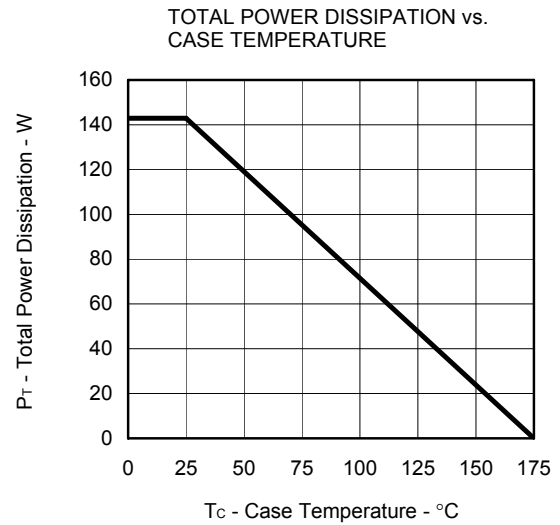
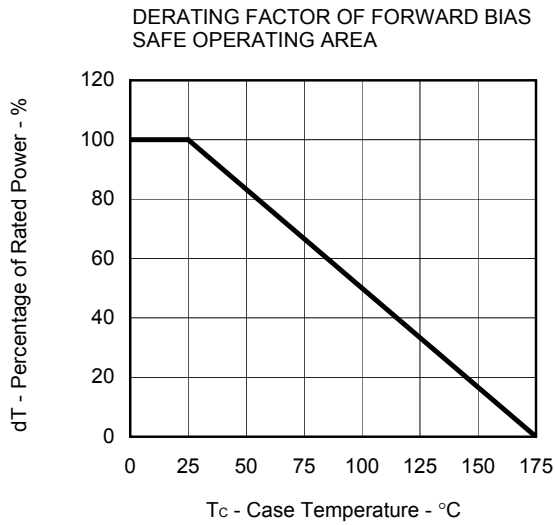
**TEST CIRCUIT 2 SWITCHING TIME**



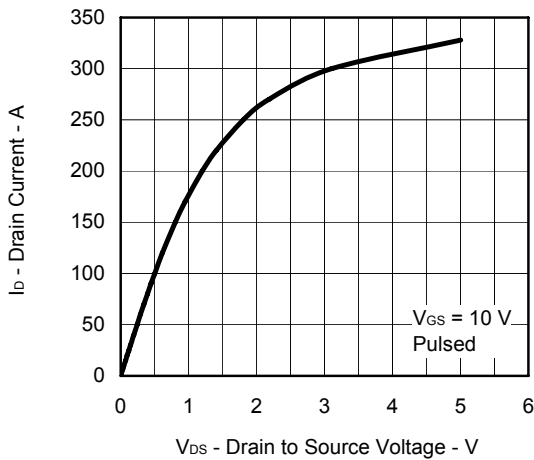
**TEST CIRCUIT 3 GATE CHARGE**



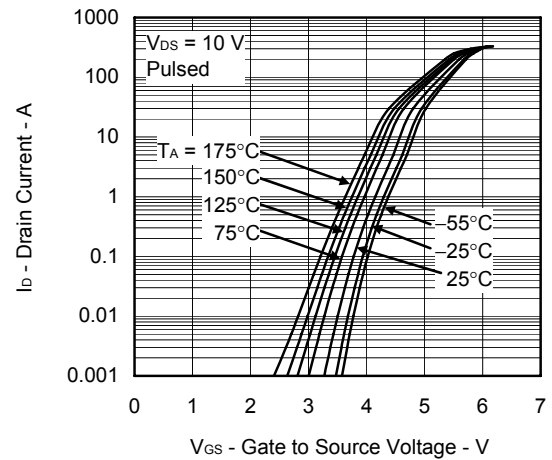
TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)



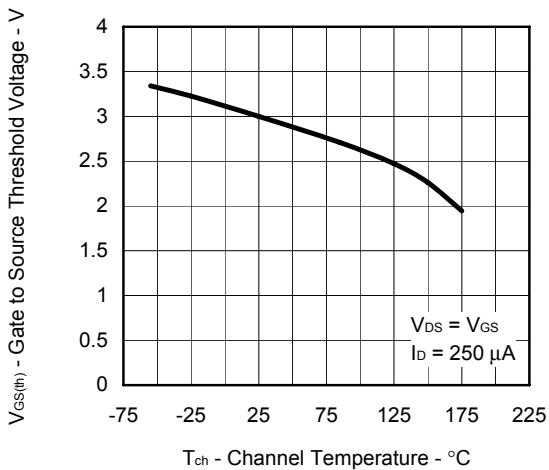
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



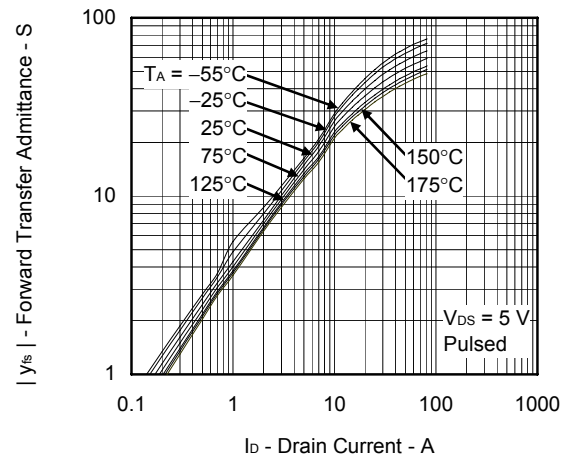
FORWARD TRANSFER CHARACTERISTICS



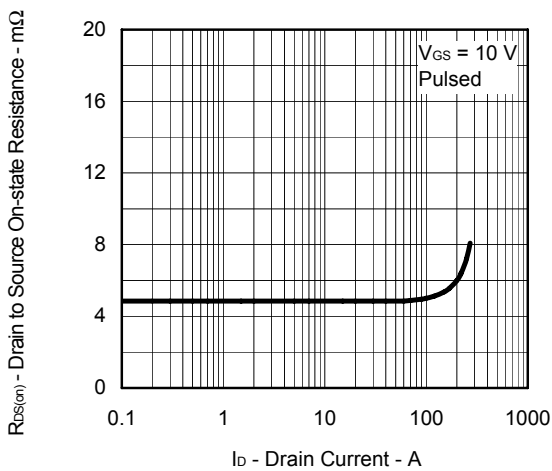
GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE



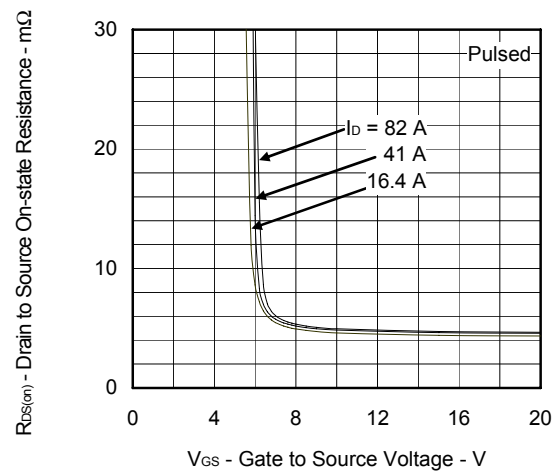
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



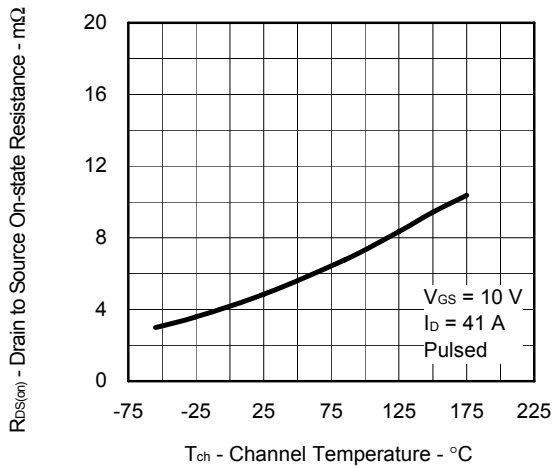
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



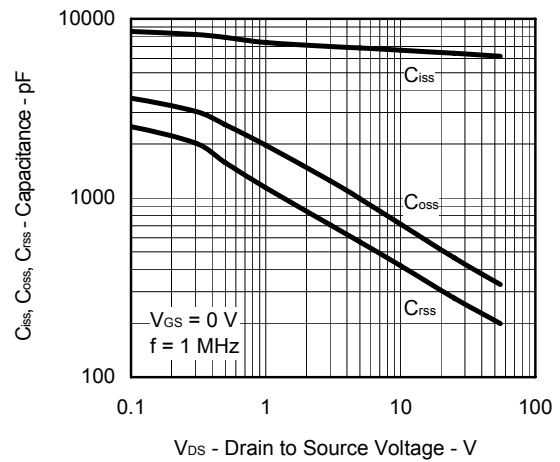
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



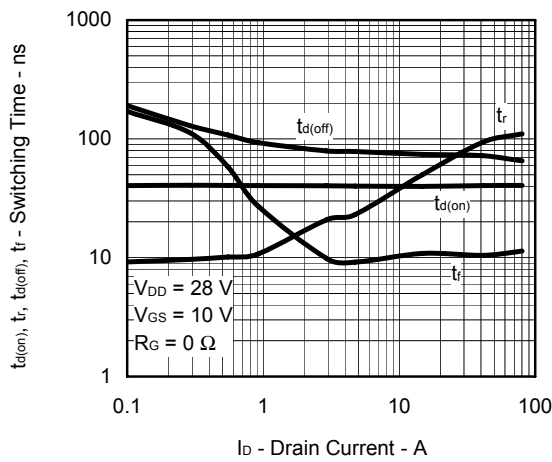
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



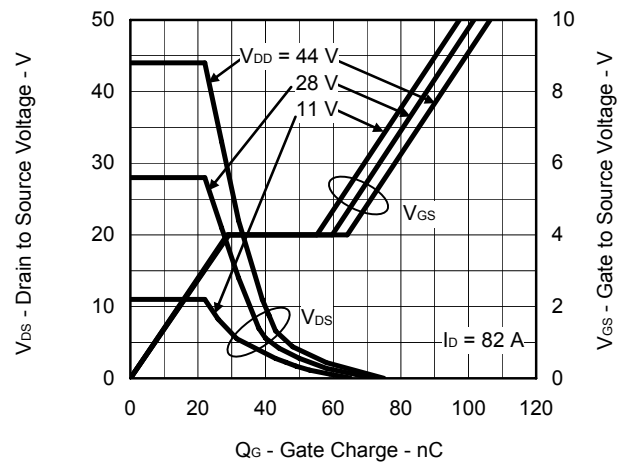
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



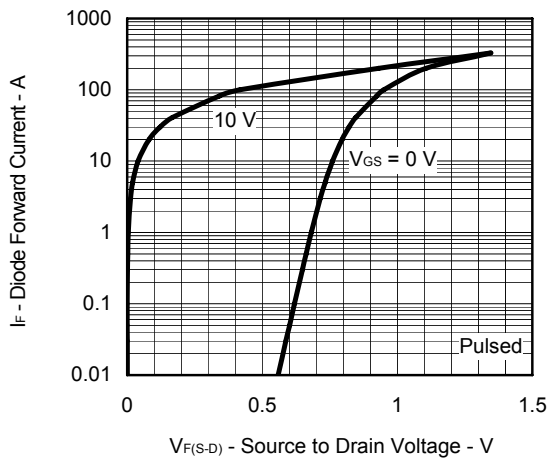
SWITCHING CHARACTERISTICS



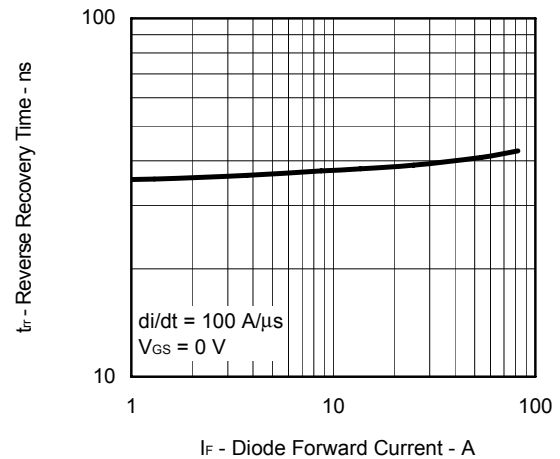
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE

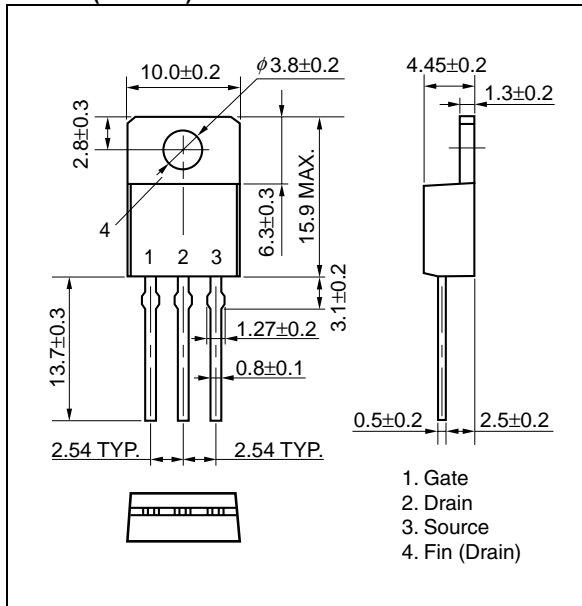


REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT

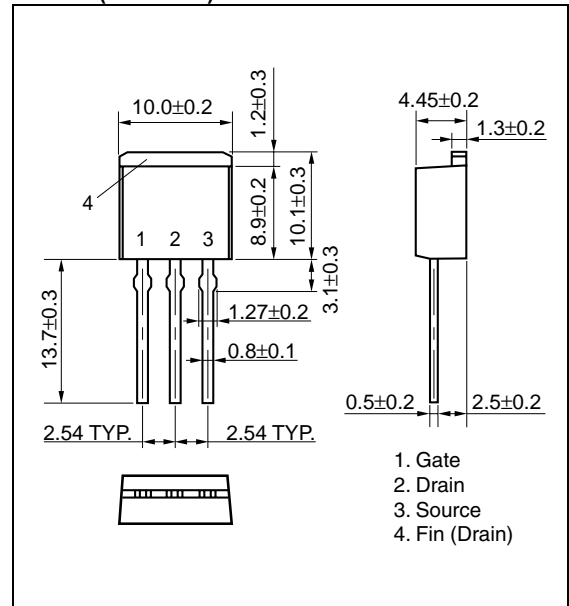


PACKAGE DRAWINGS (Unit: mm)

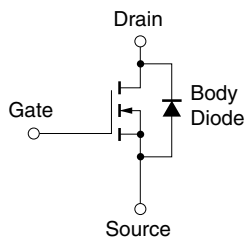
TO-220 (MP-25K)



TO-262 (MP-25SK)



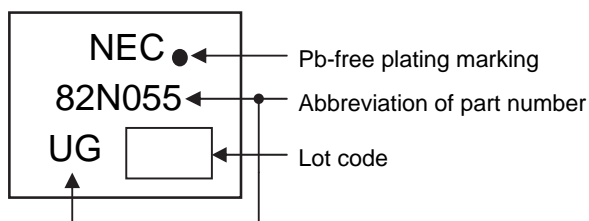
EQUIVALENT CIRCUIT



**Remark** Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.



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These products should be soldered and mounted under the following recommended conditions.

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For technical information, see the following website.

Semiconductor Device Mount Manual (<http://www.necel.com/pkg/en/mount/index.html>)

| Soldering Method                               | Soldering Conditions  | Recommended Condition Symbol |
|--|---|------------------------------|
| Wave soldering<br>NP82N055MUG,<br>NP82N055NUG  | Maximum temperature (Solder temperature): 260°C or below<br>Time: 10 seconds or less<br>Maximum chlorine content of rosin flux: 0.2% (wt.) or less                      | THDWS                        |
| Partial heating<br>NP82N055MUG,<br>NP82N055NUG | Maximum temperature (Pin temperature): 350°C or below<br>Time (per side of the device): 3 seconds or less<br>Maximum chlorine content of rosin flux: 0.2% (wt.) or less | P350                         |

**Caution Do not use different soldering methods together (except for partial heating).**

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